Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2023-11-05
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

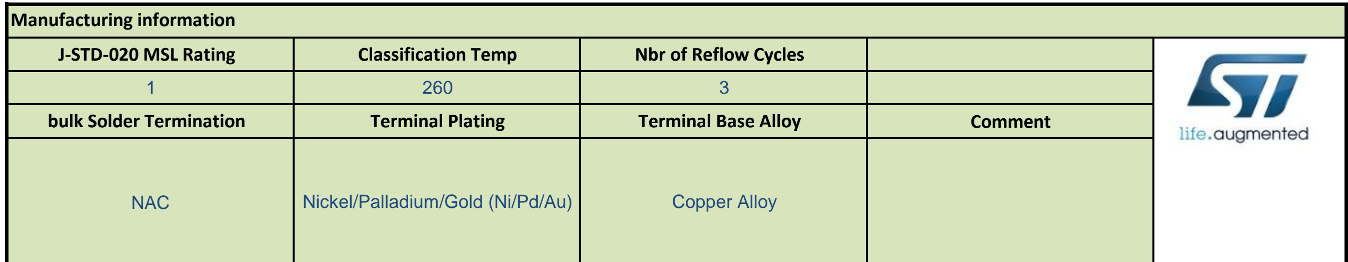
Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32C011J6M6	C0O7*443XXXZ	A	3068	2023-11-05
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	76.20	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SO	4.9x3.9x1.5	8	L bend	
Comment	Package : O7 SO 08 .15 JEDEC 0016023			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	C0O7*443XXXZ				5000000.0	1000012.2
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	2.577	mg	supplier	die	Silicon (Si)	7440-21-3		2.493	mg	967404	32717
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	1552	52
				supplier	metallization	Copper (Cu)	7440-50-8		0.036	mg	13970	472
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.012	mg	4657	157
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	3492	118
				supplier	Passivation	Silicon Oxide	7631-86-9		0.023	mg	8925	302
Leadframe (C194 + NiPdAu + Ag)	M-011 Other inorganic materials	30.428	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.420	mg	966873	386089
				supplier	alloy	Iron (Fe)	7439-89-6		0.708	mg	23268	9291
				supplier	alloy	Zinc (Zn)	7440-66-6		0.036	mg	1183	472
				supplier	alloy	Phosphorus (P)	7723-14-0		0.025	mg	822	328
				supplier	coating	Nickel (Ni)	7440-02-0		0.114	mg	3747	1496
				supplier	coating	Palladium (Pd)	7440-05-3		0.007	mg	230	92
				supplier	coating	Gold (Au)	7440-57-5		0.114	mg	3747	1496
				supplier	coating	Silver (Ag)	7440-22-4		0.004	mg	131	52
Glue Epoxy (8601S-25)	M-011 Other inorganic materials	0.480	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		0.421	mg	878000	5531
				supplier	glue or soft solder	Isobornyl Methacrylate	7534-94-3		0.048	mg	100000	630
				supplier	glue or soft solder	Epoxy Resin	Proprietary		0.011	mg	22000	139
Bonding wires (Au)	M-011 Other inorganic materials	0.303	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.303	mg	1000000	3976
Encapsulation (EME-G700KC)	M-011 Other inorganic materials	42.413	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		3.181	mg	75000	41745
				supplier	Moulding Compound	Phenol Resin	Proprietary		2.121	mg	50000	27830
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		36.730	mg	866000	482017
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.212	mg	5000	2783
				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.170	mg	4000	2226